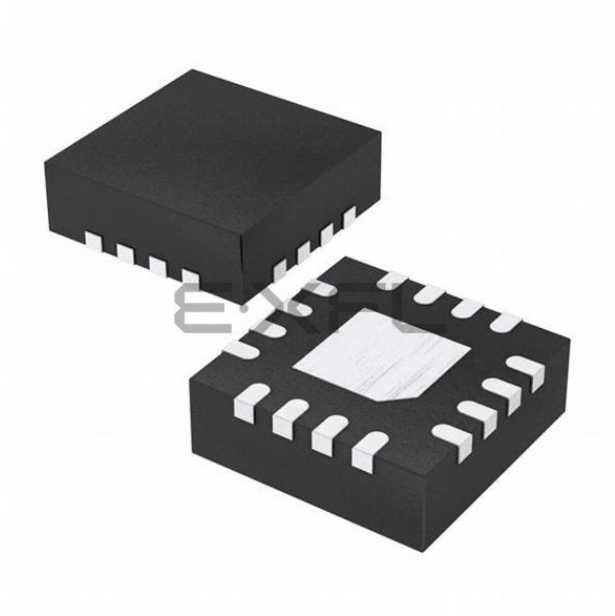

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	16-VQFN Exposed Pad
Supplier Device Package	16-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1823-e-ml

Peripheral Features (Continued)

- Data Signal Modulator module
  - Selectable modulator and carrier sources
- SR Latch:
  - Multiple Set/Reset input options
  - Emulates 555 Timer applications

TABLE 1: PIC12(L)F1822/1840/PIC16(L)F182X/1847 FAMILY TYPES

Device	Data Sheet Index	Program Memory Flash (words)	Data EEPROM (bytes)	Data SRAM (bytes)	I/O's(2)	10-bit ADC (ch)	CapSense (ch)	Comparators	Timers (8/16-bit)	EUSART	MSSP (I^2C™/SPI)	ECCP (Full-Bridge) ECCP (Half-Bridge) CCP	SR Latch	Debug(1)	XLP
PIC12(L)F1822	(1)	2K	256	128	6	4	4	1	2/1	1	1	0/1/0	Y	I/H	Y
PIC12(L)F1840	(2)	4K	256	256	6	4	4	1	2/1	1	1	0/1/0	Y	I/H	Y
PIC16(L)F1823	(1)	2K	256	128	12	8	8	2	2/1	1	1	1/0/0	Y	I/H	Y
PIC16(L)F1824	(3)	4K	256	256	12	8	8	2	4/1	1	1	1/1/2	Y	I/H	Y
PIC16(L)F1825	(4)	8K	256	1024	12	8	8	2	4/1	1	1	1/1/2	Y	I/H	Y
PIC16(L)F1826	(5)	2K	256	256	16	12	12	2	2/1	1	1	1/0/0	Y	I/H	Y
PIC16(L)F1827	(5)	4K	256	384	16	12	12	2	4/1	1	2	1/1/2	Y	I/H	Y
PIC16(L)F1828	(3)	4K	256	256	18	12	12	2	4/1	1	1	1/1/2	Y	I/H	Y
PIC16(L)F1829	(4)	8K	256	1024	18	12	12	2	4/1	1	2	1/1/2	Y	I/H	Y
PIC16(L)F1847	(6)	8K	256	1024	16	12	12	2	4/1	1	2	1/1/2	Y	I/H	Y

Note 1: I - Debugging, Integrated on Chip; H - Debugging, available using Debug Header.

2: One pin is input-only.

Data Sheet Index: (Unshaded devices are described in this document.)

1: DS41413 PIC12(L)F1822/PIC16(L)F1823 Data Sheet, 8/14-Pin Flash Microcontrollers.

2: DS41441 PIC12(L)F1840 Data Sheet, 8-Pin Flash Microcontrollers.

3: DS41419 PIC16(L)F1824/1828 Data Sheet, 28/40/44-Pin Flash Microcontrollers.

4: DS41440 PIC16(L)F1825/1829 Data Sheet, 14/20-Pin Flash Microcontrollers.

5: DS41391 PIC16(L)F1826/1827 Data Sheet, 18/20/28-Pin Flash Microcontrollers.

6: DS41453 PIC16(L)F1847 Data Sheet, 18/20/28-Pin Flash Microcontrollers.

Note: For other small form-factor package availability and marking information, please visit www.microchip.com/packaging or contact your local sales office.

FIGURE 2: 14-PIN DIAGRAM FOR PIC16(L)F1823

PDIP, SOIC, TSSOP

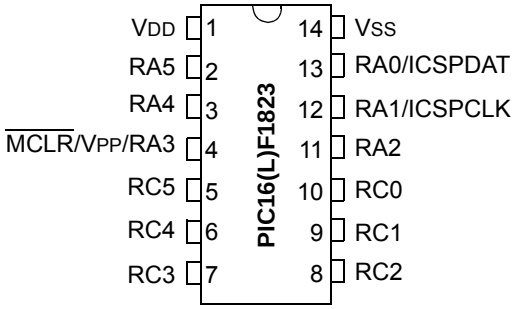
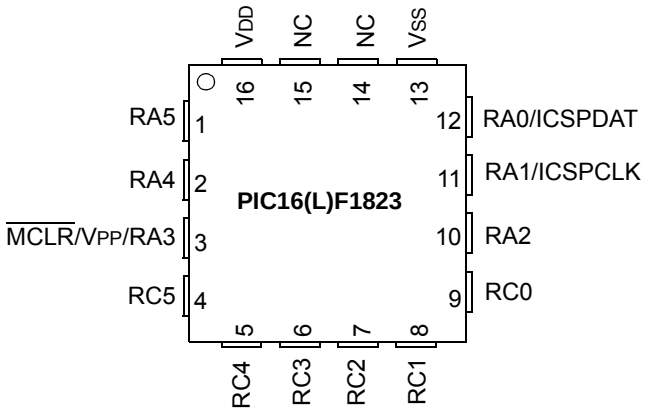


FIGURE 3: 16-PIN DIAGRAM FOR PIC16(L)F1823

QFN, UQFN



REGISTER 4-1: CONFIGURATION WORD 1

R/P-1/1	R/P-1/1	R/P-1/1	R/P-1/1	R/P-1/1	R/P-1/1
FCMEN	IESO	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		$\overline{\text{CPD}}$
bit 13					bit 8

R/P-1/1	R/P-1/1	R/P-1/1	R/P-1/1	R/P-1/1	R/P-1/1	R/P-1/1	R/P-1/1
$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		FOSC<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13 **FCMEN:** Fail-Safe Clock Monitor Enable bit
1 = Fail-Safe Clock Monitor is enabled
0 = Fail-Safe Clock Monitor is disabled

bit 12 **IESO:** Internal External Switchover bit
1 = Internal/External Switchover mode is enabled
0 = Internal/External Switchover mode is disabled

bit 11 **$\overline{\text{CLKOUTEN}}$:** Clock Out Enable bit
If FOSC configuration bits are set to LP, XT, HS modes:
This bit is ignored, CLKOUT function is disabled. Oscillator function on the CLKOUT pin
All other FOSC modes:
1 = CLKOUT function is disabled. I/O function on the CLKOUT pin
0 = CLKOUT function is enabled on the CLKOUT pin

bit 10-9 **BOREN<1:0>:** Brown-out Reset Enable bits(1)
11 = BOR enabled
10 = BOR enabled during operation and disabled in Sleep
01 = BOR controlled by SBOREN bit of the BORCON register
00 = BOR disabled

bit 8 **$\overline{\text{CPD}}$:** Data Code Protection bit(2)
1 = Data memory code protection is disabled
0 = Data memory code protection is enabled

bit 7 **$\overline{\text{CP}}$:** Code Protection bit(3)
1 = Program memory code protection is disabled
0 = Program memory code protection is enabled

bit 6 **MCLRE:** $\overline{\text{MCLR}}$/VPP Pin Function Select bit
If LVP bit = 1:
This bit is ignored.
If LVP bit = 0:
1 = $\overline{\text{MCLR}}$/VPP pin function is $\overline{\text{MCLR}}$; Weak pull-up enabled.
0 = $\overline{\text{MCLR}}$/VPP pin function is digital input; $\overline{\text{MCLR}}$ internally disabled; Weak pull-up under control of the WPUA register.

bit 5 **$\overline{\text{PWRTE}}$:** Power-up Timer Enable bit(1)
1 = PWRT disabled
0 = PWRT enabled

bit 4-3 **WDTE<1:0>:** Watchdog Timer Enable bit
11 = WDT enabled
10 = WDT enabled while running and disabled in Sleep
01 = WDT controlled by the SWDTEN bit in the WDTCON register
00 = WDT disabled

Note 1: Enabling Brown-out Reset does not automatically enable Power-up Timer.
2: The entire data EEPROM will be erased when the code protection is turned off during an erase.
3: The entire program memory will be erased when the code protection is turned off.

REGISTER 10-1: WDTCON: WATCHDOG TIMER CONTROL REGISTER

U-0	U-0	R/W-0/0	R/W-1/1	R/W-0/0	R/W-1/1	R/W-1/1	R/W-0/0
—	—	WDTPS<4:0>					SWDTEN
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-m/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5-1 **WDTPS<4:0>:** Watchdog Timer Period Select bits

Bit Value = Prescale Rate

00000 = 1:32 (Interval 1 ms typ)
00001 = 1:64 (Interval 2 ms typ)
00010 = 1:128 (Interval 4 ms typ)
00011 = 1:256 (Interval 8 ms typ)
00100 = 1:512 (Interval 16 ms typ)
00101 = 1:1024 (Interval 32 ms typ)
00110 = 1:2048 (Interval 64 ms typ)
00111 = 1:4096 (Interval 128 ms typ)
01000 = 1:8192 (Interval 256 ms typ)
01001 = 1:16384 (Interval 512 ms typ)
01010 = 1:32768 (Interval 1s typ)
01011 = 1:65536 (Interval 2s typ) (Reset value)
01100 = 1:131072 (2^{17}) (Interval 4s typ)
01101 = 1:262144 (2^{18}) (Interval 8s typ)
01110 = 1:524288 (2^{19}) (Interval 16s typ)
01111 = 1:1048576 (2^{20}) (Interval 32s typ)
10000 = 1:2097152 (2^{21}) (Interval 64s typ)
10001 = 1:4194304 (2^{22}) (Interval 128s typ)
10010 = 1:8388608 (2^{23}) (Interval 256s typ)

10011 = Reserved. Results in minimum interval (1:32)
•
•
•
11111 = Reserved. Results in minimum interval (1:32)

bit 0 **SWDTEN:** Software Enable/Disable for Watchdog Timer bit

If WDTE<1:0> = 00:
This bit is ignored.
If WDTE<1:0> = 01:
1 = WDT is turned on
0 = WDT is turned off
If WDTE<1:0> = 1x:
This bit is ignored.

16.1.5 INTERRUPTS

The ADC module allows for the ability to generate an interrupt upon completion of an Analog-to-Digital conversion. The ADC Interrupt Flag is the ADIF bit in the PIR1 register. The ADC Interrupt Enable is the ADIE bit in the PIE1 register. The ADIF bit must be cleared in software.

Note 1:	The ADIF bit is set at the completion of every conversion, regardless of whether or not the ADC interrupt is enabled.
2:	The ADC operates during Sleep only when the FRC oscillator is selected.

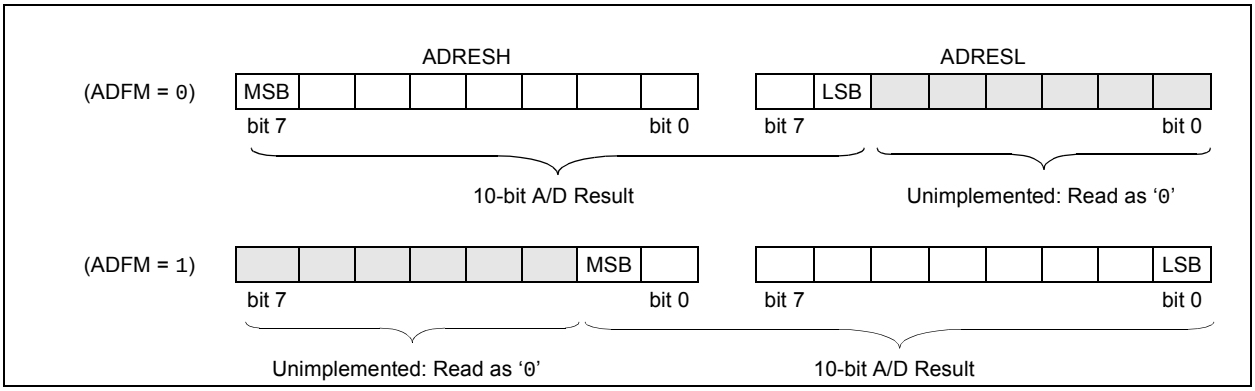
This interrupt can be generated while the device is operating or while in Sleep. If the device is in Sleep, the interrupt will wake-up the device. Upon waking from Sleep, the next instruction following the SLEEP instruction is always executed. If the user is attempting to wake-up from Sleep and resume in-line code execution, the GIE and PEIE bits of the INTCON register must be disabled. If the GIE and PEIE bits of the INTCON register are enabled, execution will switch to the Interrupt Service Routine.

16.1.6 RESULT FORMATTING

The 10-bit A/D conversion result can be supplied in two formats, left justified or right justified. The ADFM bit of the ADCON1 register controls the output format.

Figure 16-3 shows the two output formats.

FIGURE 16-3: 10-BIT A/D CONVERSION RESULT FORMAT



16.3 A/D Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 16-4. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), refer to Figure 16-4. **The maximum recommended impedance for analog sources is 10 kΩ.** As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an A/D acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 16-1 may be used. This equation assumes that 1/2 LSb error is used (1,024 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 16-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ *5.0V* V_{DD}

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$
$$= 2\mu s + T_C + [(Temperature - 25°C)(0.05\mu s/°C)]$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD}$$;[1] V_{CHOLD} *charged to within 1/2 lsb*

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD}$$;[2] V_{CHOLD} *charge response to* $V_{APPLIED}$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right)$$;combining [1] and [2]

Note: Where n = number of bits of the ADC.

Solving for T_C*:*

$$T_C = -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/2047)$$
$$= -12.5pF(1k\Omega + 7k\Omega + 10k\Omega)\ ln(0.0004885)$$
$$= 1.72\mu s$$

Therefore:

$$T_{ACQ} = 2\mu s + 1.72\mu s + [(50°C - 25°C)(0.05\mu s/°C)]$$
$$= 4.97\mu s$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

REGISTER 23-1: MDCON: MODULATION CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-1/1	R/W-0/0	R-0/0	U-0	U-0	R/W-0/0
MDEN	MDOE	MDSLR	MDOPOL	MDOUT	—	—	MDBIT
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **MDEN:** Modulator Module Enable bit
- 1 = Modulator module is enabled and mixing input signals
- 0 = Modulator module is disabled and has no output

bit 6 **MDOE:** Modulator Module Pin Output Enable bit
- 1 = Modulator pin output enabled
- 0 = Modulator pin output disabled

bit 5 **MDSLR:** MDOUT Pin Slew Rate Limiting bit
- 1 = MDOUT pin slew rate limiting enabled
- 0 = MDOUT pin slew rate limiting disabled

bit 4 **MDOPOL:** Modulator Output Polarity Select bit
- 1 = Modulator output signal is inverted
- 0 = Modulator output signal is not inverted

bit 3 **MDOUT:** Modulator Output bit

Displays the current output value of the Modulator module.(1)

bit 2-1 **Unimplemented:** Read as '0'

bit 0 **MDBIT:** Allows software to manually set modulation source input to module(2)
- 1 = Modulator uses High Carrier source
- 0 = Modulator uses Low Carrier source

Note 1: The modulated output frequency can be greater and asynchronous from the clock that updates this register bit, the bit value may not be valid for higher speed modulator or carrier signals.

2: MDBIT must be selected as the modulation source in the MDSRC register for this operation.

24.3.6 OPERATION IN SLEEP MODE

In Sleep mode, the TMR2 register will not increment and the state of the module will not change. If the CCP1 pin is driving a value, it will continue to drive that value. When the device wakes up, TMR2 will continue from its previous state.

24.3.7 CHANGES IN SYSTEM CLOCK FREQUENCY

The PWM frequency is derived from the system clock frequency. Any changes in the system clock frequency will result in changes to the PWM frequency. See **Section 5.0 "Oscillator Module (With Fail-Safe Clock Monitor)"** for additional details.

24.3.8 EFFECTS OF RESET

Any Reset will force all ports to Input mode and the CCP registers to their Reset states.

24.3.9 ALTERNATE PIN LOCATIONS

This module incorporates I/O pins that can be moved to other locations with the use of the alternate pin function register, APFCON. To determine which pins can be moved and what their default locations are upon a Reset, see **Section 12.1 "Alternate Pin Function"** for more information.

TABLE 24-8: SUMMARY OF REGISTERS ASSOCIATED WITH STANDARD PWM

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
APFCON	RXDTSEL	SDOSEL	SSSEL	—	T1GSEL	TXCKSEL	P1BSEL(2)	CCP1SEL(2)	114
CCP1CON	P1M<1:0>		DC1B<1:0>		CCP1M<3:0>				213
CCPR1L	Capture/Compare/PWM Register x Low Byte (LSB)								191
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	86
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	87
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	89
PR2	Timer2 Period Register								176*
T2CON	—	T2OUTPS<3:0>				TMR2ON	T2CKPS<:0>1		178
TMR2	Timer2 Module Register								176*
TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	117
TRISC(1)	—	—	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	121

Legend: — = Unimplemented location, read as '0'. Shaded cells are not used by the PWM.

* Page provides register information.

Note 1: PIC16(L)F1823 only.

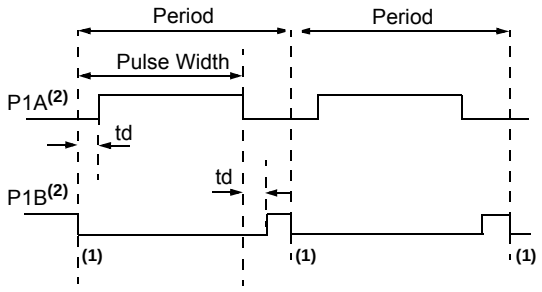
2: PIC12(L)F1822 only.

24.4.5 PROGRAMMABLE DEAD-BAND DELAY MODE

In Half-Bridge applications where all power switches are modulated at the PWM frequency, the power switches normally require more time to turn off than to turn on. If both the upper and lower power switches are switched at the same time (one turned on, and the other turned off), both switches may be on for a short period of time until one switch completely turns off. During this brief interval, a very high current (*shoot-through current*) will flow through both power switches, shorting the bridge supply. To avoid this potentially destructive shoot-through current from flowing during switching, turning on either of the power switches is normally delayed to allow the other switch to completely turn off.

In Half-Bridge mode, a digitally programmable dead-band delay is available to avoid shoot-through current from destroying the bridge power switches. The delay occurs at the signal transition from the non-active state to the active state. See Figure 24-16 for illustration. The lower seven bits of the associated PWM1CON register (Register 24-3) sets the delay period in terms of microcontroller instruction cycles (TCY or 4 TOSC).

FIGURE 24-16: EXAMPLE OF HALF-BRIDGE PWM OUTPUT

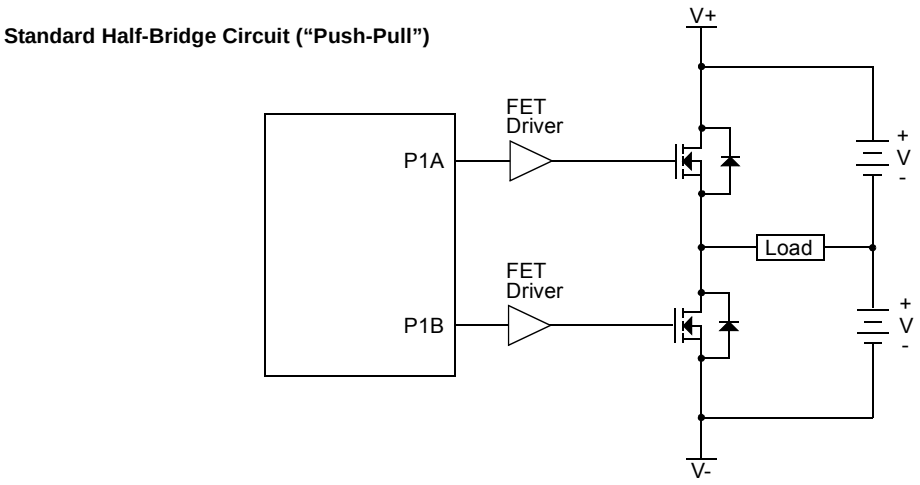


td = Dead-Band Delay

Note 1: At this time, the TMR2 register is equal to the PR2 register.

2: Output signals are shown as active-high.

FIGURE 24-17: EXAMPLE OF HALF-BRIDGE APPLICATIONS



REGISTER 24-2: CCP1AS: CCP1 AUTO-SHUTDOWN CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
CCP1ASE	CCP1AS<2:0>			PSS1AC<1:0>		PSS1BD<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **CCP1ASE:** CCP1 Auto-Shutdown Event Status bit
1 = A shutdown event has occurred; CCP1 outputs are in shutdown state
0 = CCP1 outputs are operating

bit 6-4 **CCP1AS<2:0>:** CCP1 Auto-Shutdown Source Select bits
000 = Auto-shutdown is disabled
001 = Comparator C1 output high(1)
010 = Comparator C2 output high(1, 2)
011 = Either Comparator C1 or C2 high(1, 2)
100 = VIL on FLT0 pin
101 = VIL on FLT0 pin or Comparator C1 high(1)
110 = VIL on FLT0 pin or Comparator C2 high(1, 2)
111 = VIL on FLT0 pin or Comparator C1 or Comparator C2 high(1, 2)

bit 3-2 **PSS1AC<1:0>:** Pins P1A and P1C Shutdown State Control bits(2)
00 = Drive pins P1A and P1C to '0'
01 = Drive pins P1A and P1C to '1'
1x = Pins P1A and P1C tri-state

bit 1-0 **PSS1BD<1:0>:** Pins P1B and P1D Shutdown State Control bits(2)
00 = Drive pins P1B and P1D to '0'
01 = Drive pins P1B and P1D to '1'
1x = Pins P1B and P1D tri-state

Note 1: If C1SYNC is enabled, the shutdown will be delayed by Timer1.
2: C2, P1C and P1D available on PIC16(L)F1823 only.

TABLE 27-3: SUMMARY OF REGISTERS ASSOCIATED WITH CAPACITIVE SENSING

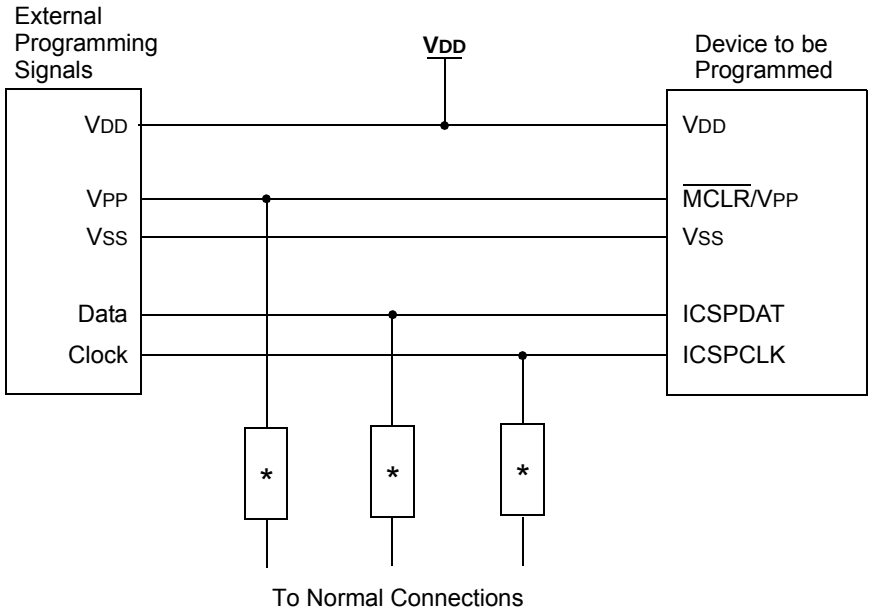
Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	—	ANSA4	—	ANSA2	ANSA1	ANSA0	118
ANSELC(1)	—	—	—	—	ANSC3	ANSC2	ANSC1	ANSC0	122
CPSCON0	CPSON	CPSRM	—	—	CPSRNG1	CPSRNG0	CPSOUT	T0XCS	302
CPSCON1	—	—	—	—	CPSCH3(1)	CPSCH2(1)	CPSCH1	CPSCH0	303
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	86
OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS2	PS1	PS0	164
T1CON	TMR1CS1	TMR1CS0	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON	173
TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	117
TRISC(1)	—	—	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	121

Legend: — = Unimplemented locations, read as '0'. Shaded cells are not used by the CPS module.
Note 1: PIC16(L)F1823 only.

For additional interface recommendations, refer to your specific device programmer manual prior to PCB design.

It is recommended that isolation devices be used to separate the programming pins from other circuitry. The type of isolation is highly dependent on the specific application and may include devices such as resistors, diodes, or even jumpers. See Figure 28-4 for more information.

FIGURE 28-4: TYPICAL CONNECTION FOR ICSP™ PROGRAMMING



* Isolation devices (as required).

CALL **Call Subroutine**

Syntax:	[*label*] CALL k
Operands:	0 ≤ k ≤ 2047
Operation:	(PC)+ 1→ TOS, k → PC<10:0>, (PCLATH<4:3>) → PC<12:11>
Status Affected:	None
Description:	Call Subroutine. First, return address (PC + 1) is pushed onto the stack. The eleven-bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a 2-cycle instruction.

CALLW **Subroutine Call With W**

Syntax:	[*label*] CALLW
Operands:	None
Operation:	(PC) +1 → TOS, (W) → PC<7:0>, (PCLATH<6:0>) → PC<14:8>
Status Affected:	None
Description:	Subroutine call with W. First, the return address (PC + 1) is pushed onto the return stack. Then, the contents of W is loaded into PC<7:0>, and the contents of PCLATH into PC<14:8>. CALLW is a 2-cycle instruction.

CLRF **Clear f**

Syntax:	[*label*] CLRF f
Operands:	0 ≤ f ≤ 127
Operation:	00h → (f) 1 → Z
Status Affected:	Z
Description:	The contents of register ‘f’ are cleared and the Z bit is set.

CLRW **Clear W**

Syntax:	[*label*] CLRW
Operands:	None
Operation:	00h → (W) 1 → Z
Status Affected:	Z
Description:	W register is cleared. Zero bit (Z) is set.

CLRWDT **Clear Watchdog Timer**

Syntax:	[*label*] CLRWDT
Operands:	None
Operation:	00h → WDT 0 → WDT prescaler, 1 → $\overline{TO}$ 1 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Description:	CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

COMF **Complement f**

Syntax:	[*label*] COMF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	($\bar{f}$) → (destination)
Status Affected:	Z
Description:	The contents of register ‘f’ are complemented. If ‘d’ is ‘0’, the result is stored in W. If ‘d’ is ‘1’, the result is stored back in register ‘f’.

DECF **Decrement f**

Syntax:	[*label*] DECF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(f) - 1 → (destination)
Status Affected:	Z
Description:	Decrement register ‘f’. If ‘d’ is ‘0’, the result is stored in the W register. If ‘d’ is ‘1’, the result is stored back in register ‘f’.

30.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS}, PIC12F1822/16F1823 ..... -0.3V to +6.5V
Voltage on V_{DD} with respect to V_{SS}, PIC12LF1822/16LF1823 ..... -0.3V to +4.0V
Voltage on $\overline{MCLR}$ with respect to Vss ..... -0.3V to +9.0V
Voltage on all other pins with respect to V_{SS} ..... -0.3V to (V_{DD} + 0.3V)
Total power dissipation(1) ..... 800 mW
Maximum current out of V_{SS} pin, -40°C ≤ T_A ≤ +85°C for industrial ..... 210 mA
Maximum current out of V_{SS} pin, -40°C ≤ T_A ≤ +125°C for extended ..... 95 mA
Maximum current into V_{DD} pin, -40°C ≤ T_A ≤ +85°C for industrial ..... 150 mA
Maximum current into V_{DD} pin, -40°C ≤ T_A ≤ +125°C for extended ..... 70 mA
Clamp current, I_K (V_{PIN} < 0 or V_{PIN} > V_{DD}) ..... ± 20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OI} \times I_{OL})$.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

30.2 DC Characteristics: PIC12(L)F1822/16(L)F1823-I/E (Industrial, Extended)

PIC12LF1822/16LF1823			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
PIC12F1822/16F1823			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Device Characteristics**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**	
						VDD	**Note**
	Supply Current (IDD)(1, 2)						
D020		—	2.0	3.1	mA	3.0	FOSC = 32 MHz HS Oscillator mode **(Note 4)**
		—	2.5	3.5	mA	3.6	
D020		—	2.0	3.1	mA	3.0	FOSC = 32 MHz HS Oscillator mode **(Note 4)**
		—	2.5	3.5	mA	5.0	
D021		—	210	425	µA	1.8	FOSC = 4 MHz EXTRC mode **(Note 5)**
		—	470	800	µA	3.0	
D021		—	350	435	µA	1.8	FOSC = 4 MHz EXTRC mode **(Note 5)**
		—	550	800	µA	3.0	
		—	620	850	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; $\overline{MCLR}$ = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: 8 MHz internal RC oscillator with 4x PLL enabled.

4: 8 MHz crystal oscillator with 4x PLL enabled.

5: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be extended by the formula IR = VDD/2REXT (mA) with REXT in kΩ.

FIGURE 30-7: CLKOUT AND I/O TIMING

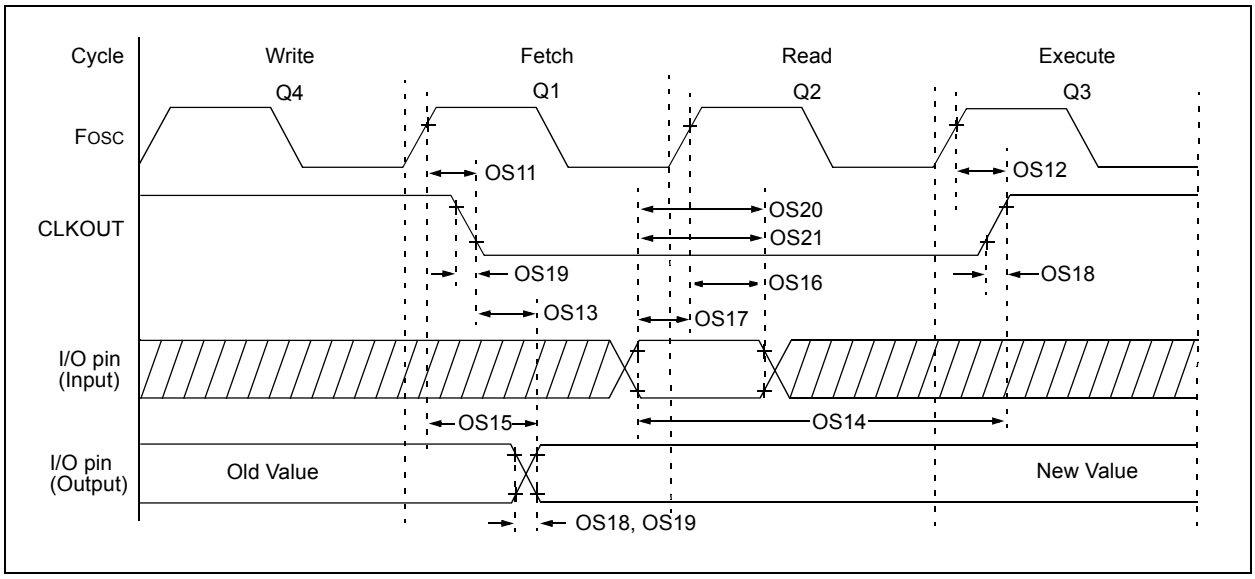


TABLE 30-19: DC CHARACTERISTICS FOR PIC12F1822/16F1823-H (High Temp.)

PIC12F1822/16F1823			Standard Operating Conditions: (unless otherwise stated) Operating Temperature: -40°C ≤ TA ≤ +150°C for High Temperature				
Param No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Condition**
D001	VDD	Supply Voltage	2.5	—	5.5	V	FOSC ≤ 32 MHz **(Note 1)**
D002*	VDR	RAM Data Retention Voltage	2.1	—	5.5	V	Device in Sleep mode
D003	VADFVR	Fixed Voltage Reference Voltage for ADC	-10	—	8	%	1.024V, VDD ≥ 2.5V 2.048V, VDD ≥ 2.5V 4.096V, VDD ≥ 4.75V
D003A	VCDAFVR	Fixed Voltage Reference Voltage for ADC	-13	—	9	%	1.024V, VDD ≥ 2.5V 2.048V, VDD ≥ 2.5V 4.096V, VDD ≥ 4.75V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: PLL required for 32 MHz operation.

TABLE 30-23: A/D CONVERTER (ADC) CHARACTERISTICS FOR PIC12F1822/16F1823-H (High Temp.)

PIC12F1822/16F1823			Standard Operating Conditions: (unless otherwise stated) Operating Temperature: -40°C ≤ TA ≤ +150°C for High Temperature				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
AD04	EOFF	Offset Error	—	—	3.5	LSB	No missing codes VREF = 3.0V

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Total Absolute Error includes integral, differential, offset and gain errors.

2: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

3: ADC VREF is from external VREF, VDD pin or FVR, whichever is selected as reference input.

TABLE 30-24: COMPARATOR SPECIFICATIONS FOR PIC12F1822/16F1823-H (High Temp.)

PIC12F1822/16F1823			Standard Operating Conditions: (unless otherwise stated) Operating Temperature: -40°C ≤ TA ≤ +150°C for High Temperature				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
CM01	VIOFF	Input Offset Voltage	—	—	±70	mV	High-Power mode, VICM = VDD/2

TABLE 30-25: CAP SENSE OSCILLATOR SPECIFICATIONS FOR PIC12F1822/16F1823-H (High Temp.)

PIC12F1822/16F1823			Standard Operating Conditions: (unless otherwise stated) Operating Temperature: -40°C ≤ TA ≤ +150°C for High Temperature				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
All	All	All	—	—	—	—	This module is not intended for use in high temperature devices.

FIGURE 31-23: IDD TYPICAL, HFINTOSC MODE, PIC12LF1822 AND PIC16LF1823 ONLY

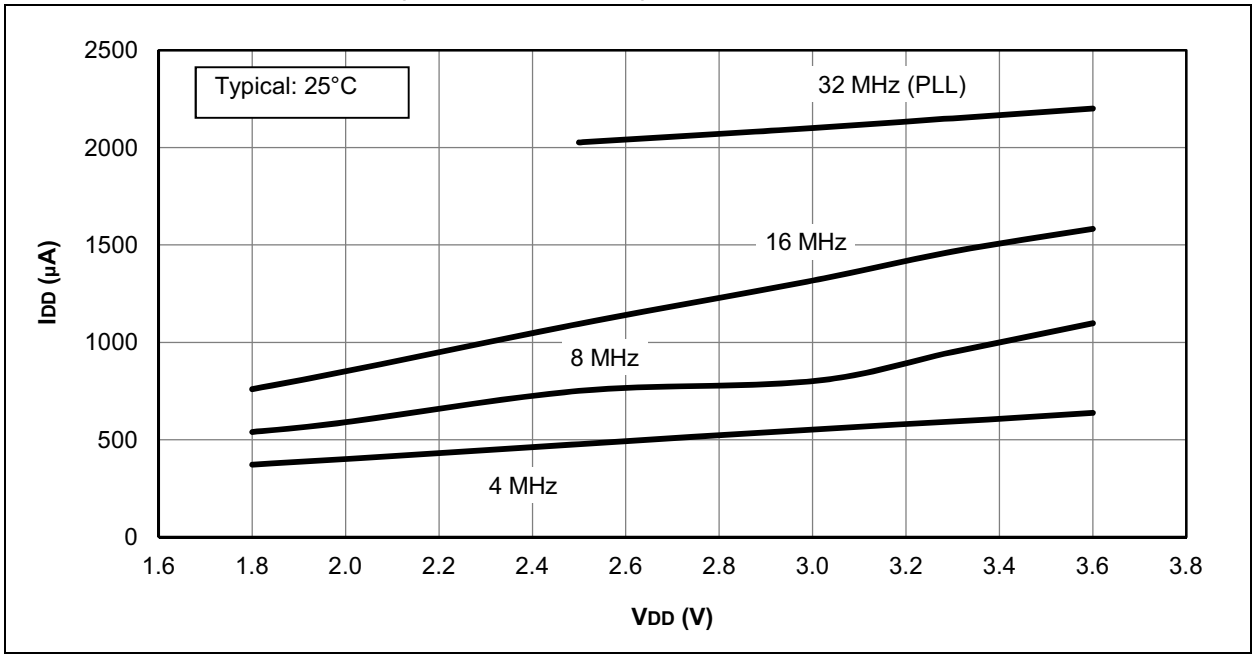
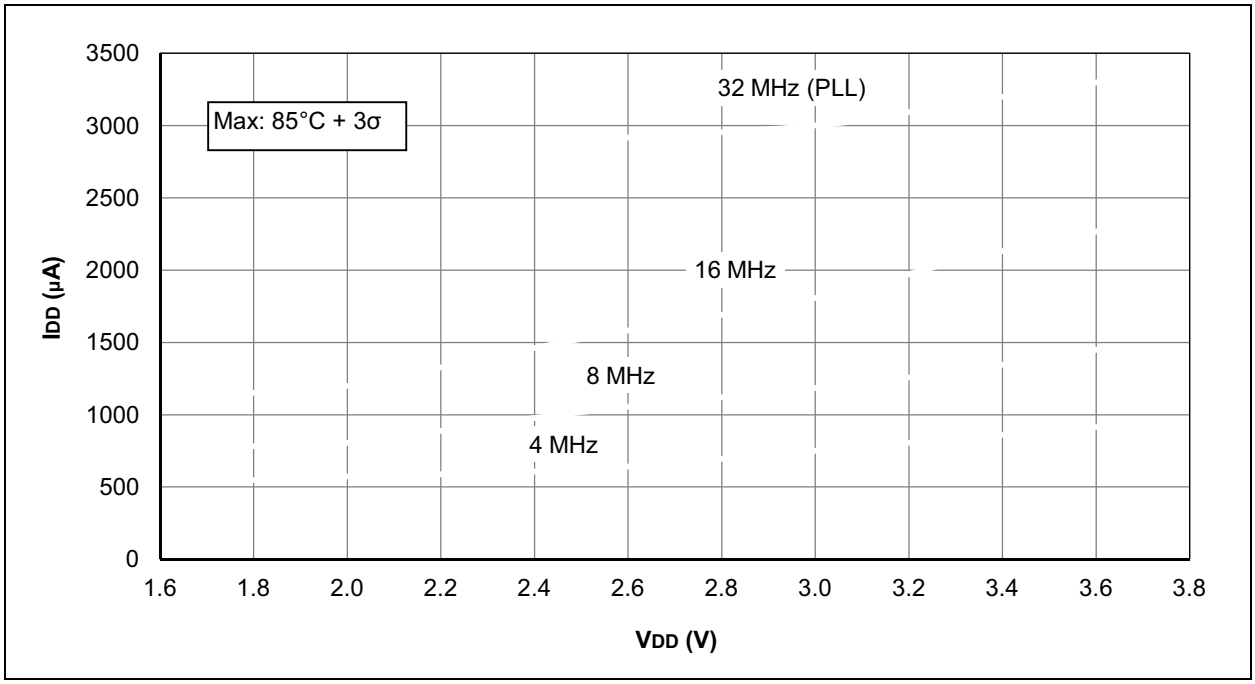
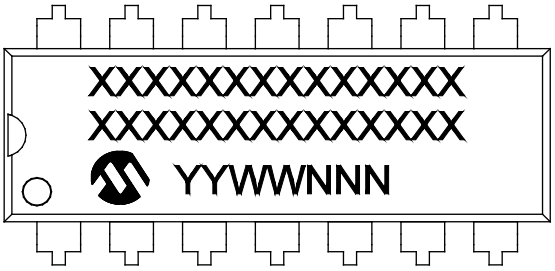


FIGURE 31-24: IDD MAXIMUM, HFINTOSC MODE, PIC12LF1822 AND PIC16LF1823 ONLY

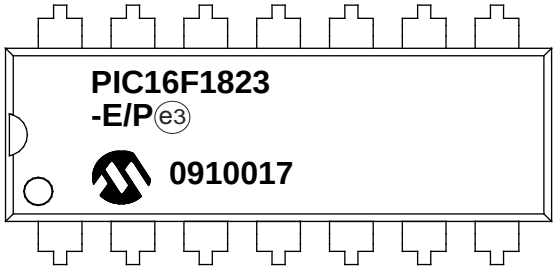


33.1 Package Marking Information (Continuation)

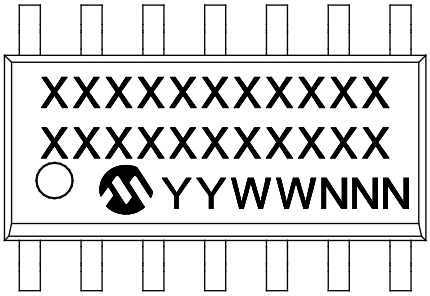
14-Lead PDIP (300 mil)



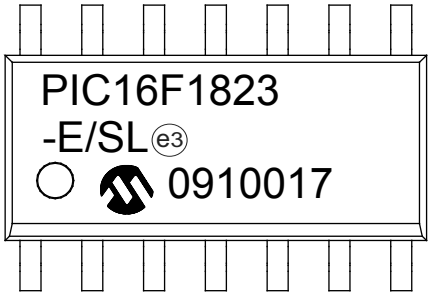
Example



14-Lead SOIC (3.90 mm)



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.